

CLAIMS

What is claimed is:

1 1. A structure comprising a metallic surface, a layer
2 of a first polymeric material and a layer of a water soluble
3 polymeric material located between the metallic surface and
4 the first polymeric material.

1 2. The structure of claim 1 wherein the metallic
2 surface is selected from the group consisting of copper,
3 gold, aluminum, silver, titanium, tantalum, tungsten,
4 niobium, alloys thereof and intermetallic compounds thereof.

1 3. The structure of claim 1 wherein the metallic
2 surface is copper or gold.

1 4. The structure of claim 1 wherein the metallic
2 surface is copper.

1 5. The structure of claim 1 wherein the first
2 polymeric material is a photoactive polymeric material.

1 6. The structure of claim 1 wherein the first
2 polymeric material is an acrylate or methacrylate based
3 polymeric material.

1 7. The structure of claim 1 wherein the water soluble
2 polymeric material is a cationic polymeric material.

1 8. The structure of claim 1 wherein the water soluble
2 polymeric material is a non-ionic polymeric material.

1 9. The structure of claim 1 wherein the water soluble
2 polymeric material is a polymer of acrylamide.

1 10. The structure of claim 1 wherein the water soluble
2 polymeric material is a polymer of amidoamine.

1 11. The structure of claim 1 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 at least about 100,000.

1 12. The structure of claim 1 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 about 500,000 to about 1,000,000.

1 13. The structure of claim 1 being an electronic
2 package which further includes a substrate upon which the
3 metallic surface is present.

1 14. The structure of claim 13 wherein the first
2 polymeric material is a photoactive polymeric material that
3 has been patterned.

1 15. A process for fabricating a structure which
2 comprises the steps of providing a metallic surface,
3 providing a water soluble ^{cationic} polymeric material on the metallic
4 surface, and ^{then} providing a layer of a non-water soluble
5 polymeric material on the water soluble polymeric material.

1 16. The process of claim 15 wherein the metallic
2 surface is selected from the group consisting of copper,
3 gold, aluminum, silver, titanium, tantalum, tungsten,
4 niobium, alloys thereof and intermetallic compounds thereof.

1 17. The process of claim 15 wherein the metallic
2 surface is copper or gold.

1 18. The process of claim 15 wherein the metallic
2 surface is copper.

1 19. The process of claim 15 wherein the non-water
2 soluble polymeric material is a photoactive polymeric
3 material.

1 20. The process of claim 15 wherein the non-water
2 soluble polymeric material is an acrylate or methacrylate
3 based polymeric material.

1 21. The process of claim 15 wherein the water soluble
2 polymeric material is a cationic polymeric material.

1 22. The process of claim 15 wherein the water soluble
2 polymeric material is a non-ionic polymeric material.

1 23. The process of claim 15 wherein the water soluble
2 polymeric material is a polymer of acrylamide.

1 24. The process of claim 15 wherein the water soluble
2 polymeric material is a polymer of amidoamine.

1 25. The process of claim 15 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 at least about 100,000.

1 26. The process of claim 15 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 about 500,000 to about 1,000,000.

1 27. A process for fabricating an electronic package
2 which comprises providing a substrate and a metallic
3 conductive layer on the substrate, providing a water soluble
4 polymeric material located on the conductive layer, *then*
5 providing a photoactive polymeric film on the water soluble
6 polymeric material, *then* imagewise exposing the photoactive
7 polymeric material to actinic light, and developing by
8 removing photoactive polymeric film.

1 28. The process of claim 27 wherein the metallic
2 surface is selected from the group consisting of copper,
3 gold, aluminum, silver, titanium, tantalum, tungsten,
4 niobium, alloys thereof and intermetallic compounds thereof.

1 29. The process of claim 27 wherein the metallic
2 surface is copper or gold.

1 30. The process of claim 27 wherein the metallic
2 surface is copper.

1 31. The process of claim 27 wherein the photoactive
2 polymeric material is an acrylate or methacrylate based
3 polymeric material.

1 32. The process of claim 27 wherein the water soluble
2 polymeric material is a cationic polymeric material.

1 33. The process of claim 27 wherein the water soluble
2 polymeric material is a non-ionic polymeric material.

1 34. The process of claim 27 wherein the water soluble
2 polymeric material is a polymer of acrylamide.

1 35. The process of claim 27 wherein the water soluble
2 polymeric material is a polymer of amidoamine.

1 36. The process of claim 27 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 at least about 100,000.

1 37. The process of claim 27 wherein the water soluble
2 polymeric material has a weight average molecular weight of
3 about 500,000 to about 1,000,000.